



PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

1765#10  
B  
4/6/00

APPLICANTS: HEINRICH HENNHÖFER ET AL.  
SERIAL NO.: 09/032,305 EXAMINER: R. KUNEMUND  
FILED: February 27, 1998 GROUP: 1765  
TITLE: PROCESS FOR TREATING A POLISHED SEMICONDUCTOR  
WAFER IMMEDIATELY AFTER THE SEMICONDUCTOR WAFER  
HAS BEEN POLISHED

AMENDMENT IN RESPONSE TO SECOND NON-FINAL OFFICE ACTION

ATTN: BOX NON-FEE AMENDMENT  
Assistant Commissioner for Patents  
Washington, D.C. 20231

Dear Sir:

In response to the Second Non-Final Office Action dated  
December 29, 1999, please amend the above-identified patent  
application as follows:

IN THE CLAIMS:

Please cancel claim 8 without prejudice, and please  
incorporate the limitations thereof into claim 1 as follows:

- B1
1. (Twice Amended) Process for treating a polished  
semiconductor wafer consisting essentially of the steps of  
polishing a surface of a semiconductor wafer;  
immediately after polishing the semiconductor wafer,

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